

IN THE CLAIMS:

1. (Currently Amended) An LED mounting module for having LED devices which are to be mounted thereon, the LED mounting module[.]] comprising:

a substrate including at least one insulation board made of an insulation material, and a wiring pattern disposed to cover at least part of a main surface of the insulation board; and

5 a plurality of reflecting members each member made of a resin material and having a reflecting hole in a position corresponding to one of each LED devices which [[are]] is to be mounted on one of main surfaces of the substrate, wherein

the substrate and the reflecting members are member has a lower surface part of which is directly adhered to part of the wiring pattern opposing the part of the lower surface, and a remainder of which is directly adhered to part of the insulation board opposing the remainder of the lower surface, each other in such a state that the main surface of the substrate is in contact with one of main surfaces of the reflecting members, and

the reflecting members are each a separate unit.

2. (Currently Amended) The LED mounting module of Claim 1, wherein

the substrate includes an insulation board made of a resin material, and a wiring pattern on one of main surfaces of the insulation board, and

[[the]] a resin material forming the insulation board contains a same resin as the

5 resin material forming the reflecting member.

3. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermosetting resin material principally containing an epoxy resin.

4. (Currently Amended) The LED mounting module of Claim 1, wherein
the wiring pattern is a surface pattern on which each LED device is to be
mounted, and

5 the surface pattern excluding an area corresponding to the reflecting hole is
entirely covered with the reflecting member.

the resin material is a thermoplastic resin material principally containing a resin
selected from a group consisting of a polyphthalimide resin, a liquid crystal polymer, a
polyphenylene sulfide resin, and a polybutylene terephthalate resin.

5. (Currently Amended) The LED mounting module of Claim [[1]] 4, wherein
the wiring pattern has another pattern being not formed on the main surface of the
insulation board, and

5 a via hole electrically connecting the other pattern and the surface pattern is
formed within the insulation board in an area corresponding to the lower surface of the reflecting
member.

the resin material contains one or more fillers to improve reflection efficiency.

6.-27. (Cancelled)